

# B82432C1183K000 Datasheet

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DiGi Electronics Part Number B82432C1183K000-DG

Manufacturer EPCOS - TDK Electronics

Manufacturer Product Number B82432C1183K000

**Description** FIXED IND 18UH 270MA 1.350HM SMD

**Detailed Description** 18 μH Unshielded Drum Core, Wirewound Inductor

270 mA 1.350hm Max 2-SMD, J-Lead

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# **Purchase and inquiry**

Manufacturer Product Number:	Manufacturer:
B82432C1183K000	EPCOS - TDK Electronics
Series:	Product Status:
SIMID	Active
Type:	Material - Core:
Drum Core, Wirewound	Ferrite
Inductance:	Tolerance:
18 μΗ	±10%
Current Rating (Amps):	Current - Saturation (Isat):
270 mA	
Shielding:	DC Resistance (DCR):
Unshielded	1.350hm Max
Q @ Freq:	Frequency - Self Resonant:
30 @ 2.52MHz	18MHz
Ratings:	Operating Temperature:
AEC-Q200	-55°C ~ 125°C
Inductance Frequency - Test:	Mounting Type:
100 kHz	Surface Mount
Package / Case:	Supplier Device Package:
2-SMD, J-Lead	1812 (4532 Metric)
Size / Dimension:	Height - Seated (Max):
0.177" L x 0.126" W (4.50mm x 3.20mm)	0.134" (3.40mm)

# **Environmental & Export classification**

8504.50.8000

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	



# **SMT** inductors

SIMID series, SIMID 1812-C

Series/Type: B82432C

Date: June 2019

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B82432C

#### **SIMID 1812-C**

<u>SMD</u>

Size 1812 (EIA) or 4532 (IEC) Rated inductance 1 ... 1000 μH Rated current 55 ... 600 mA

#### Construction

- Upright ferrite drum core
- Laser-welded winding
- Flame-retardant molding

### **Features**

- Temperature range up to +150 °C
- High Q factor
- Qualified to AEC-Q200
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020D
- RoHS-compatible

### **Applications**

- Filtering of supply voltages, coupling, decoupling
- Antenna systems
- Automotive electronics
- Telecommunications
- Industrial electronics

#### **Terminals**

- Base material CuSn6
- Layer composition Cu, Ag, Sn (lead-free)<sup>1)</sup>
- Electro-plated

### Marking

- Marking on component:
   Manufacturer and letter "C",
   L value (in nH), tolerance of L value (coded),
   date of manufacture (YWWD)
- Minimum data on reel: Manufacturer, ordering code, L value, quantity, date of packing

#### Delivery mode and packing unit

- 12-mm blister tape, wound on 330-mm Ø reel
- Packing unit: 2500 pcs./reel
- 1) Ni-barrier-plated terminals on request (B82432C\*50).



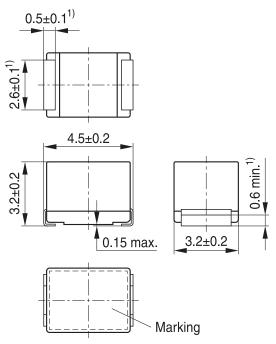


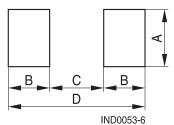
B82432C

### **SIMID 1812-C**

# **SMD**

## Dimensional drawing and layout recommendation





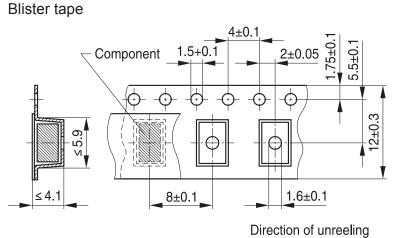
A	В	С	D
3.6	1.3	3.2	5.8

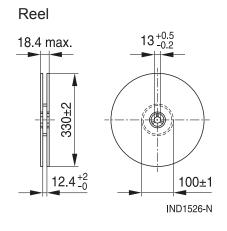
1) Soldering area

IND0083-T-E

Dimensions in mm

# **Taping and packing**





IND0561-L-E Dimensions in mm



# SMT inductors, SIMID series B82432C

# SIMID 1812-C

# **SMD**

### Technical data and measuring conditions

Rated inductance L <sub>R</sub>	Measured with impedance analyzer Agilent 4294A or equivalent at frequency f <sub>L</sub> , 0.1 V, +20 °C
Q factor Q <sub>min</sub>	Measured with impedance analyzer Agilent 4294A or equivalent at frequency f <sub>Q</sub> , +20 °C
Rated temperature T <sub>R</sub>	+85 °C
Rated current I <sub>R</sub>	Maximum permissible DC with inductance decrease $\Delta L/L_0 \leq 10\%$ and temperature increase of $\leq 30$ K at rated temperature
Self-resonance frequency f <sub>res,min</sub>	Measured with impedance analyzer Agilent 4294A/E4991A or equivalent, +20 °C
DC resistance R <sub>max</sub>	Measured at +20 °C
Solderability (lead-free)	Sn95.5Ag3.8Cu0.7: +(245 $\pm$ 5) °C, (5 $\pm$ 0.3) s Wetting of soldering area $\geq$ 90% (based on IEC 60068-2-58)
Resistance to soldering heat	+260 °C, 40 s (as referenced in JEDEC J-STD 020D)
Climatic category	55/150/56 (to IEC 60068-1)
Storage conditions	Mounted: -55 °C +150 °C Packaged: -25 °C +40 °C, ≤ 75% RH
Weight	Approx. 130 mg

## **Characteristics and ordering codes**

L <sub>R</sub>	Tolerance	fL	Q <sub>min</sub>	$f_Q$	I <sub>R</sub>	R <sub>max</sub>	f <sub>res,min</sub>	Ordering code <sup>1)</sup>
μΗ		MHz		MHz	mA	Ω	MHz	
1.0	±10% ≙ K	1	40	7.96	600	0.28	200	B82432C1102K000
1.2		1	40	7.96	560	0.32	160	B82432C1122K000
1.5		1	40	7.96	535	0.35	120	B82432C1152K000
1.8		1	40	7.96	490	0.41	100	B82432C1182K000
2.2		1	40	7.96	480	0.43	90	B82432C1222K000
2.7		1	40	7.96	450	0.49	75	B82432C1272K000
3.3		1	40	7.96	425	0.55	60	B82432C1332K000
3.9		1	40	7.96	410	0.59	50	B82432C1392K000
4.7		1	40	7.96	390	0.65	40	B82432C1472K000
5.6		1	40	7.96	375	0.71	40	B82432C1562K000
6.8		1	40	7.96	360	0.78	35	B82432C1682K000
8.2		1	40	7.96	330	0.92	30	B82432C1822K000

<sup>1)</sup> For Ni-barrier-plated terminals replace the last two digits "00" by "50".



B82432C

**SIMID 1812-C** 

### <u>SMD</u>

### Characteristics and ordering codes

L <sub>R</sub>	Tolerance	$f_L$	Q <sub>min</sub>	$f_Q$	I <sub>R</sub>	R <sub>max</sub>	f <sub>res,min</sub>	Ordering code <sup>1)2)</sup>
μΗ		MHz		MHz	mA	Ω	MHz	
10	±10% ≙ K	1	40	7.96	320	0.98	28	B82432C1103K000
12		0.1	30	2.52	300	1.10	24	B82432C1123K000
15		0.1	30	2.52	280	1.25	21	B82432C1153K000
18		0.1	30	2.52	270	1.35	18	B82432C1183K000
22		0.1	30	2.52	260	1.45	16	B82432C1223K000
27		0.1	30	2.52	245	1.65	13	B82432C1273K000
33	±5% ≙ J	0.1	30	2.52	230	1.85	13	B82432C1333+000
39	±10% ≙ K	0.1	30	2.52	220	2.05	12	B82432C1393+000
47		0.1	30	2.52	210	2.3	12	B82432C1473+000
56		0.1	30	2.52	200	2.5	11	B82432C1563+000
68		0.1	30	2.52	190	2.8	10	B82432C1683+000
82		0.1	30	2.52	175	3.2	9	B82432C1823+000
100		0.1	30	0.796	145	4.7	8	B82432C1104+000
120		0.1	30	0.796	140	5.2	8	B82432C1124+000
150		0.1	30	0.796	130	6.1	7	B82432C1154+000
180		0.1	30	0.796	120	6.9	6	B82432C1184+000
220		0.1	30	0.796	115	7.5	6	B82432C1224+000
270		0.1	30	0.796	90	12.5	5	B82432C1274+000
330	-	0.1	30	0.796	85	14.1	4.5	B82432C1334+000
390		0.1	30	0.796	80	15.3	4.2	B82432C1394+000
470		0.1	30	0.796	75	17.5	4.0	B82432C1474+000
560		0.1	30	0.796	70	23.0	3.5	B82432C1564+000
680		0.1	30	0.796	65	25.0	3.3	B82432C1684+000
820		0.1	30	0.796	60	28.0	3.0	B82432C1824+000
1000		0.1	30	0.796	55	32.0	2.8	B82432C1105+000

Closer tolerances on request.

Higher currents possible at temperatures <T $_R$  on request.

<sup>1)</sup> Replace the + by the code letter for the required inductance tolerance.

<sup>2)</sup> For Ni-barrier-plated terminals replace the last two digits "00" by "50".

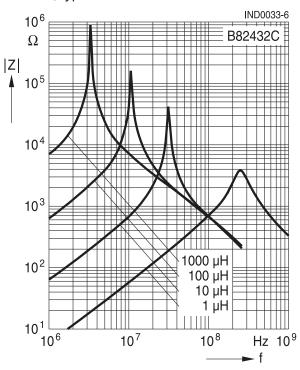


B82432C

**SIMID 1812-C** 

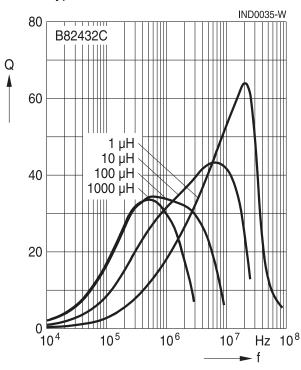
### Impedance |Z| versus frequency f

measured with impedance analyzer Agilent E4991A, typical values at +20 °C



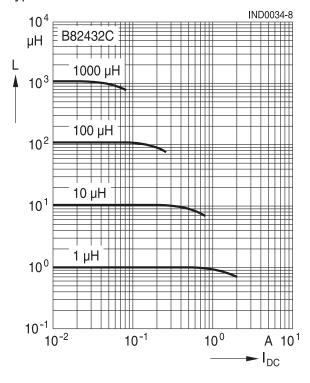
# Q factor versus frequency f

measured with impedance analyzer Agilent 4294A, typical values at +20 °C



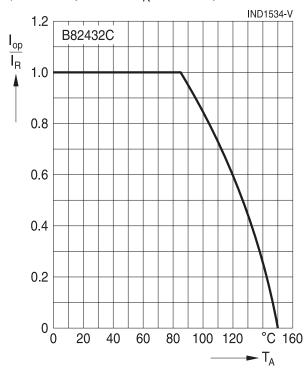
### <u>SMD</u>

Inductance L versus DC load current I<sub>DC</sub> measured with LCR meter Agilent 4285A, typical values at +20 °C



# Current derating $I_{op}/I_R$ versus ambient temperature $T_A$

(rated temperature  $T_R = +85 \, ^{\circ}C$ )





### **Cautions and warnings**

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
  Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire, wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
  - Many coating materials have a negative effect (chemically and mechanically) on the winding wires, insulation materials and connecting points. Customers are always obligated to determine whether and to what extent their coating materials influence the component. Customers are responsible and bear all risk for the use of the coating material. TDK Electronics does not assume any liability for failures of our components that are caused by the coating material.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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